

Sn100Ni+®

Sn99Ag+® • Sn98Ag+® • Sn96Ag+® • Sn95Ag+®



Electronic solders

ISO-Tin® NiGe-electronic solders

From pure metals of first melting

For use in wave, selective and dip solder baths.

Format	Dimension
ca. 0,400 kg rods	330 x 20 x 10 mm
ca. 1,000 kg rods	330 x 20 x 20 mm
ca. 3,500 kg blocks with suspension eyelet	545 x 47 x 20 mm

Also as solid wire on spools for automatic feeding and available as cone / pellets for first filling.

HASL-solders

ISO-Tin® NiGe-HASL-solders

From pure metals of first melting

For hot air tinning in the production of printed circuit boards.

Format	Dimension
ca. 0,400 kg rods	330 x 20 x 10 mm
ca. 1,000 kg rods	330 x 20 x 20 mm
ca. 3,500 kg blocks with suspension eyelet	545 x 47 x 20 mm

Also as solid wire on spools for automatic feeding and available as cone / pellets for first filling.

The alloys of the Sn100Ni+ family are well known for their good soldering properties, the glossy solder joints and the reduction of copper deposition. NiGe solder alloys have proven their reliability in many tests.

	Product	Alloy	EN ISO 9453:2014	Melting range	rec. solder wave temperature	Application
Wave soldering	Sn100Ni+®**	Sn99,3Cu0,7AgNiGe	Sn99,25Cu0,7Ni0,05	227 °C eutektic	≥ 265 °C	wave soldering selective soldering immersion soldering
	Sn100Ni+®-Refill**	Sn99,9NiGe	-	Refill for Sn100Ni+®		
	Sn99Ag+®**	Sn99Ag0,3Cu0,7NiGe	-	217 - 227 °C	≥ 260 °C	
	Sn98Ag+®**	Sn98Ag1,2Cu0,7NiGe	-	217 - 222 °C	≥ 255 °C	
	Sn96Ag+®**	Sn96,5Ag3,0Cu0,5NiGe	-	217 - 219 °C	≥ 255 °C	
	Sn95Ag+®**	Sn95,5Ag3,8Cu0,7NiGe	-	217 °C eutektic	≥ 255 °C	
HASL-Tinning	HAL-Sn100Ni+®**	Sn99,3Cu0,7AgNiGe	Sn99,25Cu0,7Ni0,05	227 °C eutektic	≥ 277 °C	hot air tinning
	HAL-Sn100Ni+®-Refill	Sn99,9NiGe	-	Refill for HAL-Sn100Ni+® (acc. Cu-content)		
	HAL-Sn99Ag+®**	Sn99Ag0,3Cu0,7NiGe	Sn99Cu0,7Ag0,3(NiGe)	227 °C eutektic	258 - 268 °C	
	HAL-Sn99Ag+®-Refill	Sn99,7Ag0,3NiGe	-	Refill for HAL-Sn99Ag+® (acc. Cu-content)		

** Fuji-Patent: DE-Patent-No. 19816671G2; US-Patent-Nr. 6.179.935B1; Japan-Patent-Nr. 3296289

All electronic solders are of course also available as copper-free REFILL solders. Our lead-free solders comply with the RoHS directive and therefore also with the ElektroG. We will be happy to provide you with a declaration of conformity.

Please note the application advantages of our NiGe-doped electronic solders. Please ask for our detailed product information.

SN100-403C



Electronic solders

ISO-Tin® SN100-403C

From pure metals of first melting

For use in wave, selective and dip solder baths.

Format	Dimension
ca. 0,250 kg triangular rods	10 x 10 x 10 x 400 mm
ca. 1,000 kg rods	330 x 20 x 20 mm
ca. 3,500 kg blocks with suspension eyelet	545 x 47 x 20 mm

Also as solid wire on spools for automatic feeding and available as cone / pellets for first filling.

HASL-solders

ISO-Tin® SN100-403CL

From pure metals of first melting

For hot air tinning in the production of printed circuit boards.

Format	Dimension
ca. 0,250 kg triangular rods	10 x 10 x 10 x 400 mm
ca. 1,000 kg rods	330 x 20 x 20 mm
ca. 3,500 kg blocks with suspension eyelet	545 x 47 x 20 mm

Also as solid wire on spools for automatic feeding and available as cone / pellets for first filling.

The alloys of the SN100-403C family are well known for their good soldering properties, the glossy solder joints and the reduction of copper deposition. The SN100-403C solder has proven its reliability in many tests.

	Product	Alloy	EN ISO 9453:2014	Alloy No.	Melting range	rec. solder wave temperature	Application
wave soldering	SN100-403C *	SnCu07NiGe0,0055	Sn99,25Cu0,7Ni0,05	403	227 °C eutektic	≥ 265 °C	wave soldering selective soldering immersion soldering
	SN100-403Ce *	SnNiGe0,0055	-		Refill for SN100-403C	≥ 265 °C	
	SN100-403CS *	SnCu07NiGe0,01	Sn99,25Cu0,7Ni0,05	403	227 °C eutektic	≥ 265 °C	
	SN100-403CeS *	SnNiGe0,01	-		Refill for SN100-403CS	≥ 265 °C	
HASL-Tinning	SN100-403CL *	SnCu07NiGe0,0055	Sn99,25Cu0,7Ni0,05	403	227 °C eutektic	≥ 277 °C	hot air tinning
	SN100-403CLe *	SnNiGe0,0055	-		Refill for SN100-403CL	≥ 277 °C	
	SN100-403CLe(+)*	SnNi0,15Ge0,0055	-		Refill for SN100-403CL	≥ 277 °C	
	SN100-403CLS *	SnCu07NiGe0,01	Sn99,25Cu0,7Ni0,05	403	227 °C eutektic	≥ 277 °C	
	SN100-403CLeS *	SnNiGe0,01	-		Refill for SN100-403CLS	≥ 277 °C	
	SN100-403CLeS(+)*	SnNi0,15Ge0,01	-		Refill for SN100-403CLS	≥ 277 °C	

* manufactured according to NIHON SUPERIOR patent: DE patent no. 69918758; European patent no. 0985486

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